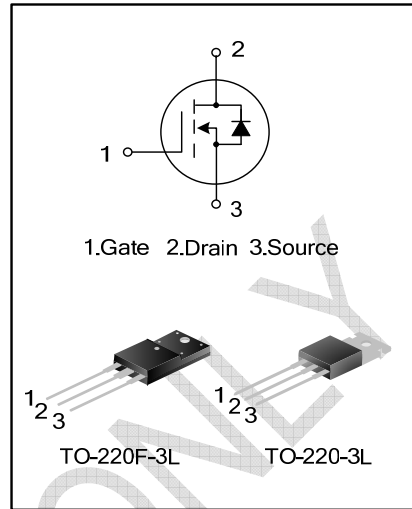


8A, 600V N-CHANNEL MOSFET

GENERAL DESCRIPTION

SVF8N60T/F is an N-channel enhancement mode power MOS field effect transistor which is produced using Silan proprietary F-Cell™ structure DMOS technology. The improved planar stripe cell and the improved guard ring terminal have been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

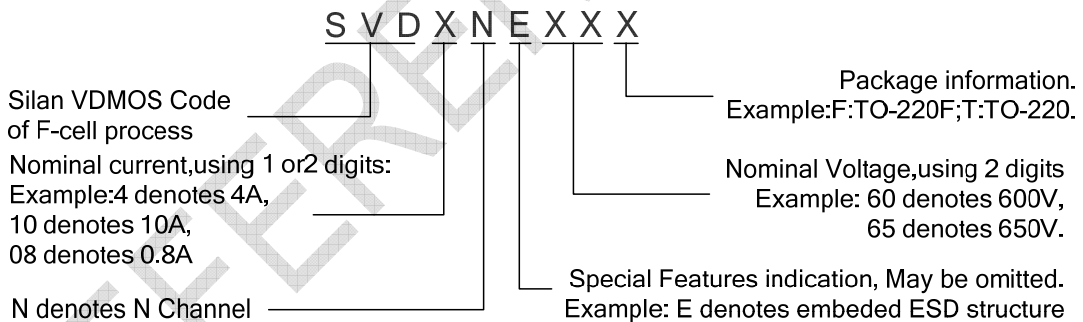
These devices are widely used in AC-DC power suppliers, DC-DC converters and H-bridge PWM motor drivers.



FEATURES

- * 8A,600V, $R_{DS(on)}$ (typ) =0.96Ω@ V_{GS} =10V
- * Low gate charge
- * Low Crss
- * Fast switching
- * Improved dv/dt capability

NOMENCLATURE



ORDERING SPECIFICATIONS

Part No.	Package	Marking	Material	Packing
SVF8N60T	TO-220-3L	SVF8N60T	Pb free	Tube
SVF8N60F	TO-220F-3L	SVF8N60F	Pb free	Tube

ABSOLUTE MAXIMUM RATINGS ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

Characteristics	Symbol	Ratings		Unit
		SVF8N60T	SVF8N60F	
Drain-Source Voltage	V_{DS}	600		V
Gate-Source Voltage	V_{GS}	± 30		V
Drain Current	I_D	8.0		A
Drain Current Pulsed	I_{DM}	28		A
Power Dissipation($T_C=25^{\circ}\text{C}$) -Derate above 25°C	P_D	147	48	W
		1.18	0.38	W/ $^{\circ}\text{C}$
Single Pulsed Avalanche Energy (Note 1)	E_{AS}	658		mJ
Operation Junction Temperature	T_J	$-55 \sim +150$		$^{\circ}\text{C}$
Storage Temperature	T_{stg}	$-55 \sim +150$		$^{\circ}\text{C}$

THERMAL CHARACTERISTICS

Characteristics	Symbol	Ratings		Unit
		SVF8N60T	SVF8N60F	
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.85	2.6	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	120	$^{\circ}\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain -Source Breakdown Voltage	$B_{V_{DSS}}$	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	600	--	--	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=600\text{V}, V_{GS}=0\text{V}$	--	--	10	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 30\text{V}, V_{DS}=0\text{V}$	--	--	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu\text{A}$	2.0	--	4.0	V
Static Drain- Source On State Resistance	$R_{DS(on)}$	$V_{GS}=10\text{V}, I_D=4\text{A}$	--	0.96	1.2	Ω
Input Capacitance	C_{iss}	$V_{DS}=25\text{V}, V_{GS}=0\text{V},$ $f=1.0\text{MHz}$	--	1057	--	pF
Output Capacitance	C_{oss}		--	85	--	
Reverse Transfer Capacitance	C_{rss}		--	10.3	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=300\text{V}, I_D=8.0\text{A},$ $R_G=25\Omega$ (Note 2,3)	--	13.6	--	ns
Turn-on Rise Time	t_r		--	51	--	
Turn-off Delay Time	$t_{d(off)}$		--	74.5	--	
Turn-off Fall Time	t_f		--	56.2	--	
Total Gate Charge	Q_g	$V_{DS}=480\text{V}, I_D=8.0\text{A},$ $V_{GS}=10\text{V}$ (Note 2,3)	--	25.1	--	nC
Gate-Source Charge	Q_{gs}		--	4.6	--	
Gate-Drain Charge	Q_{gd}		--	10.4	--	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

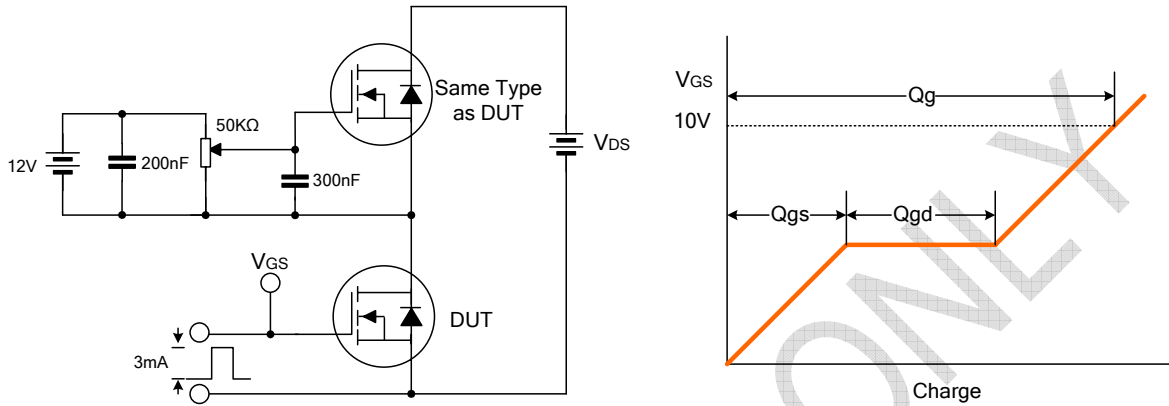
Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_S	Integral Reverse P-N Junction Diode in the MOSFET	--	--	8.0	A
Pulsed Source Current	I_{SM}		--	--	28	
Diode Forward Voltage	V_{SD}	$I_S=8.0A, V_{GS}=0V$	--	--	1.4	V
Reverse Recovery Time	T_{rr}	$I_S=8.0A, V_{GS}=0V,$ $dI_F/dt=100A/\mu S$	--	356	--	ns
Reverse Recovery Charge	Q_{rr}		--	3.1	--	μC

Notes:

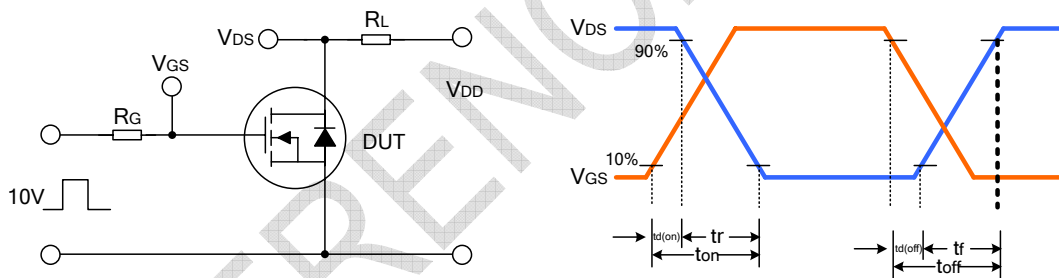
1. $L=30mH, I_{AS}=5.64A, V_{DD}=185V, R_G=25\Omega$, starting $T_J=25^\circ C$;
2. Pulse Test: Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$;
3. Essentially independent of operating temperature.

TYPICAL TEST CIRCUIT

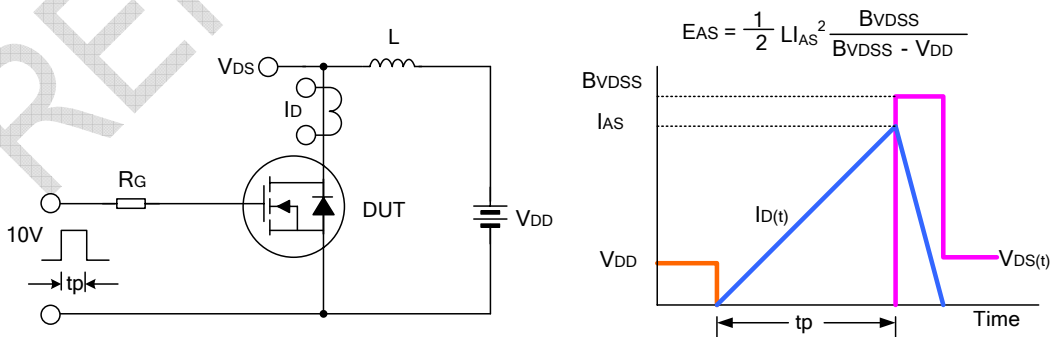
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



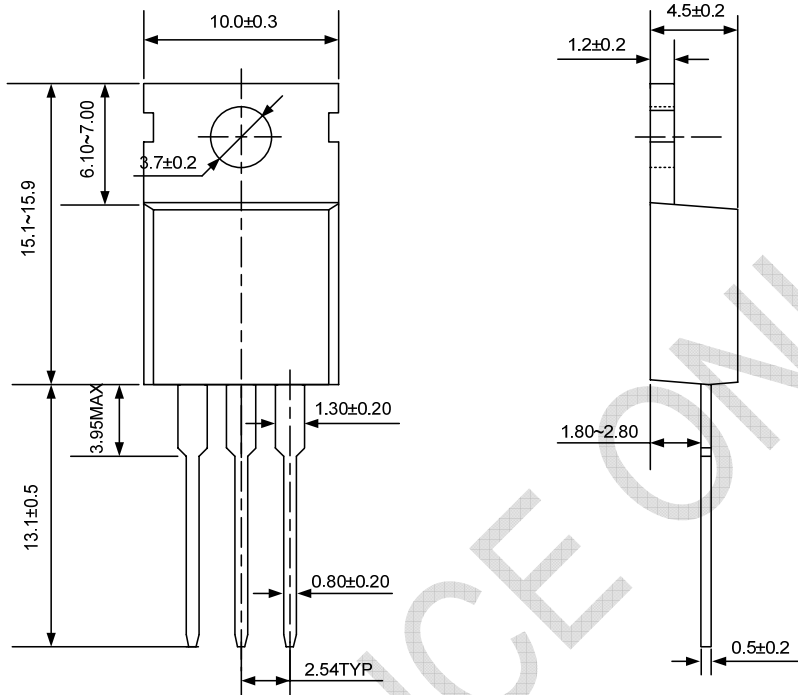
Unclamped Inductive Switching Test Circuit & Waveform



PACKAGE OUTLINE

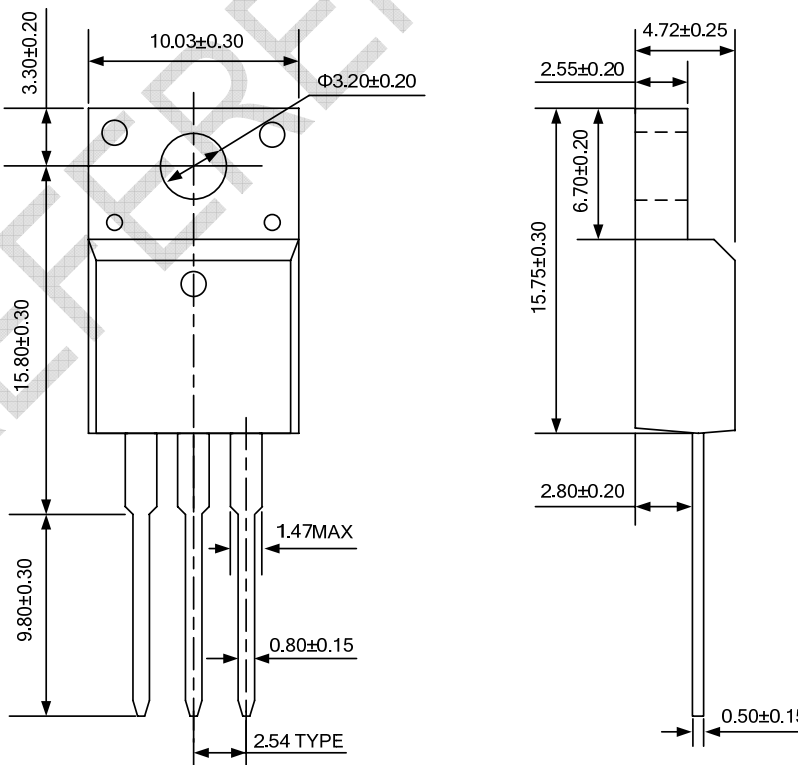
TO-220-3L

UNIT: mm



TO-220F-3L

UNIT: mm





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- Silan will supply the best possible product for customers!

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